

SIPMOS® Power-Transistor

Feature

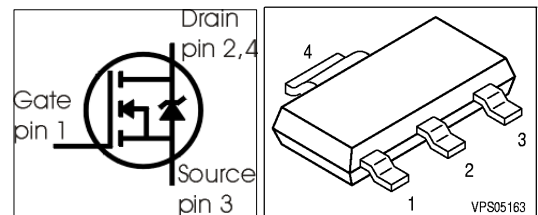
- N-Channel
- Enhancement mode
- Logic Level
- dv/dt rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101



Product Summary

V_{DS}	600	V
$R_{DS(on)}$	45	Ω
I_D	0.12	A

PG-SOT223



Type	Package	RoHS compliant	Tape and Reel Information	Marking	Packaging
BSP125	PG-SOT223	Yes	L6433: 4000 pcs/reel	BSP125	Non dry
BSP125	PG-SOT223	Yes	L6327: 1000 pcs/reel	BSP125	Non dry

Maximum Ratings, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$	I_D	0.12 0.1	A
Pulsed drain current $T_A=25^\circ\text{C}$	$I_{D\text{ puls}}$	0.48	
Reverse diode dv/dt $I_S=0.12\text{A}$, $V_{DS}=480\text{V}$, $di/dt=200\text{A}/\mu\text{s}$, $T_{j\text{max}}=175^\circ\text{C}$	dv/dt	6	kV/ μs
Gate source voltage	V_{GS}	± 20	V
ESD Class (JESD22-A114-HBM)		1A (>250V, <500V)	
Power dissipation $T_A=25^\circ\text{C}$, $T_A=25$	P_{tot}	1.8	W
Operating and storage temperature IEC climatic category; DIN IEC 68-1	T_j , T_{stg}	-55... +150	$^\circ\text{C}$
		55/150/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - soldering point (Pin 4)	R_{thJS}	-	-	25	K/W
SMD version, device on PCB:	R_{thJA}				
@ min. footprint @ 6 cm ² cooling area ¹⁾		-	-	115 70	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0, I_D=0.25\text{mA}$	$V_{(BR)DSS}$	600	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=94\mu\text{A}$	$V_{GS(th)}$	1.3	1.9	2.3	
Zero gate voltage drain current $V_{DS}=600\text{V}, V_{GS}=0, T_j=25^\circ\text{C}$ $V_{DS}=600\text{V}, V_{GS}=0, T_j=125^\circ\text{C}$	I_{DSS}	-	-	0.1 5	μA
Gate-source leakage current $V_{GS}=20\text{V}, V_{DS}=0$	I_{GSS}	-	10	100	
Drain-source on-state resistance $V_{GS}=4.5\text{V}, I_D=0.11\text{A}$	$R_{DS(on)}$	-	26	60	Ω
Drain-source on-state resistance $V_{GS}=10\text{V}, I_D=0.12\text{A}$	$R_{DS(on)}$	-	25	45	

¹⁾Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic Characteristics

Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 0.1\text{A}$	0.06	0.18	-	S
Input capacitance	C_{iss}	$V_{GS} = 0$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	-	100	150	pF
Output capacitance	C_{oss}		-	8.2	12.3	
Reverse transfer capacitance	C_{rss}		-	3.2	4.8	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 300\text{V}$, $V_{GS} = 10\text{V}$, $I_D = 0.13\text{A}$, $R_G = 6\Omega$	-	7.7	11.6	ns
Rise time	t_r		-	14.4	21	
Turn-off delay time	$t_{d(off)}$		-	20	30	
Fall time	t_f		-	110	165	

Gate Charge Characteristics

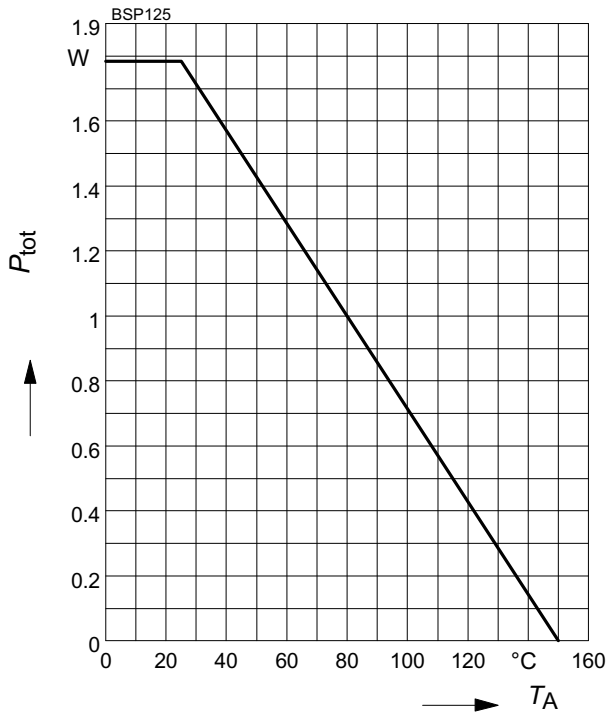
Gate to source charge	Q_{gs}	$V_{DD} = 400\text{V}$, $I_D = 0.13\text{A}$	-	0.27	0.3	nC
Gate to drain charge	Q_{gd}		-	2.3	3.5	
Gate charge total	Q_g	$V_{DD} = 400\text{V}$, $I_D = 0.13\text{A}$, $V_{GS} = 0$ to 10V	-	4.4	6.6	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 400\text{V}$, $I_D = 0.13\text{A}$	-	3.44	-	V

Reverse Diode

Inverse diode continuous forward current	I_S	$T_A = 25\text{ }^\circ\text{C}$	-	-	0.12	A
Inv. diode direct current, pulsed	I_{SM}		-	-	0.48	
Inverse diode forward voltage	V_{SD}	$V_{GS} = 0$, $I_F = 0.12\text{A}$	-	0.8	1.2	V
Reverse recovery time	t_{rr}	$V_R = 300\text{V}$, $I_F = I_S$, $di_F/dt = 100\text{A}/\mu\text{s}$	-	156	235	ns
Reverse recovery charge	Q_{rr}		-	165	250	

1 Power dissipation

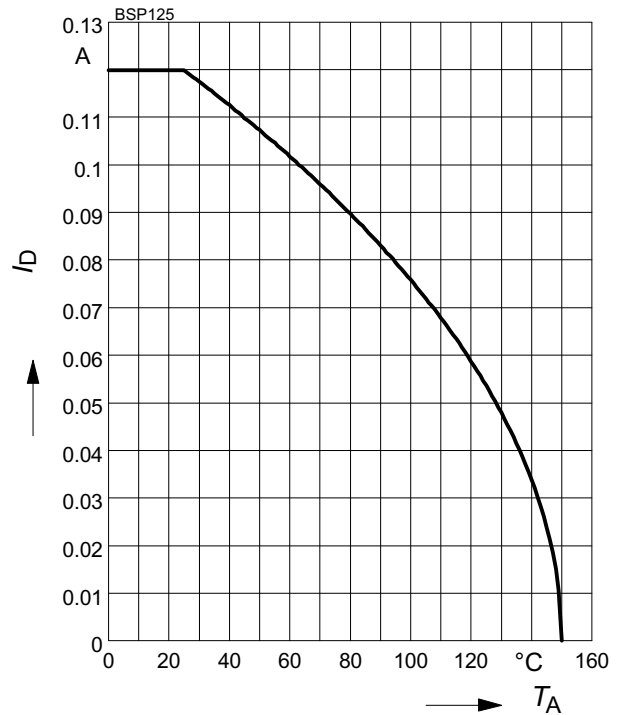
$$P_{tot} = f(T_A)$$



2 Drain current

$$I_D = f(T_A)$$

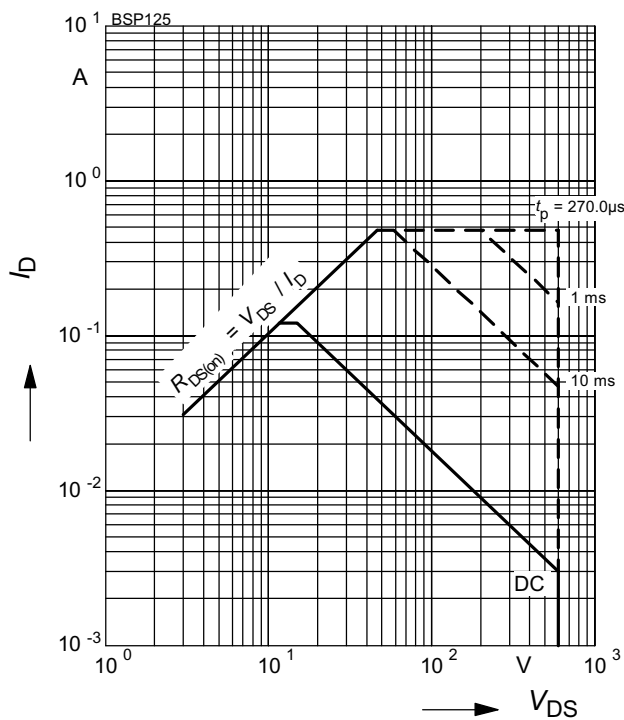
parameter: $V_{GS} \geq 10 \text{ V}$



3 Safe operating area

$$I_D = f(V_{DS})$$

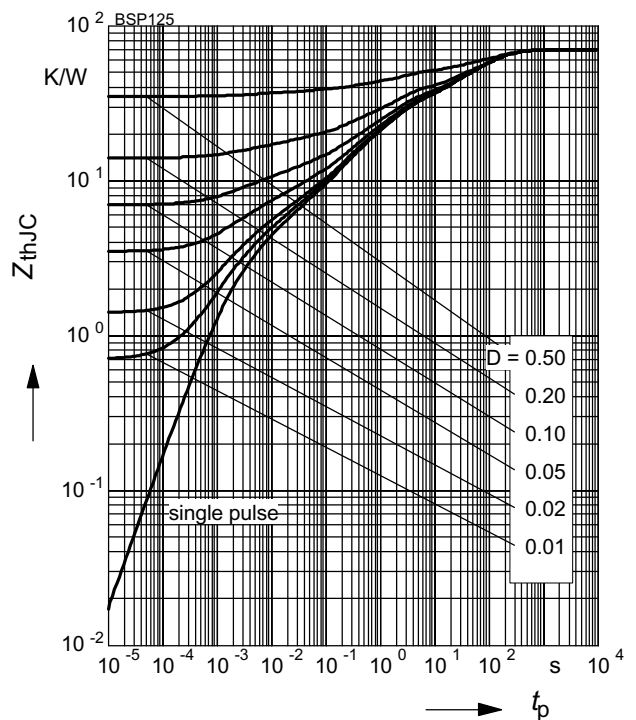
parameter: $D = 0, T_A = 25$



4 Transient thermal impedance

$$Z_{thJA} = f(t_p)$$

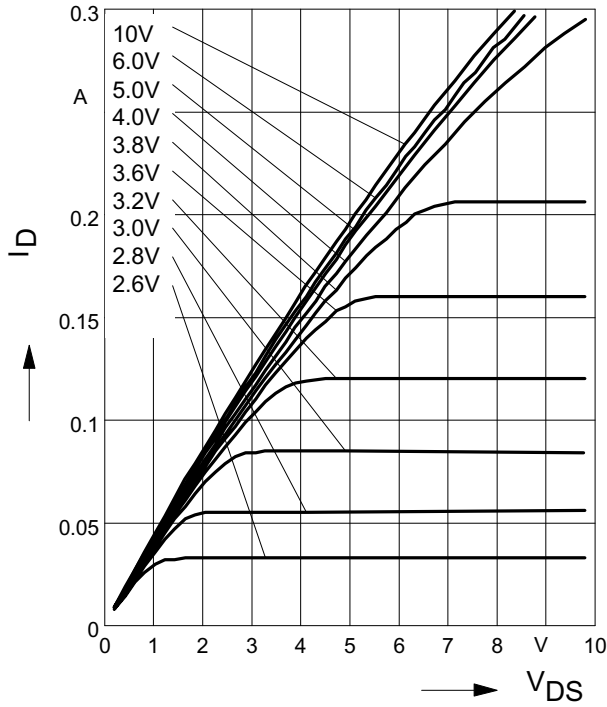
parameter: $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS})$

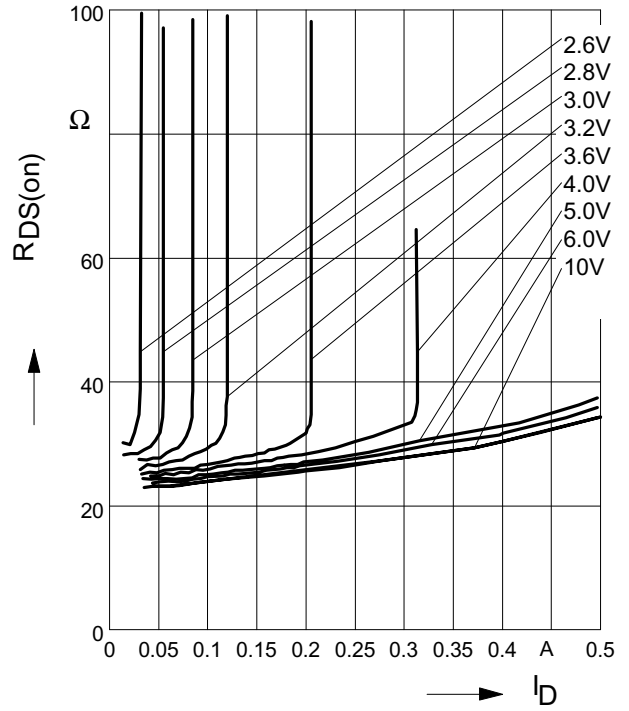
parameter: $T_j = 25\text{ }^\circ\text{C}$, V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

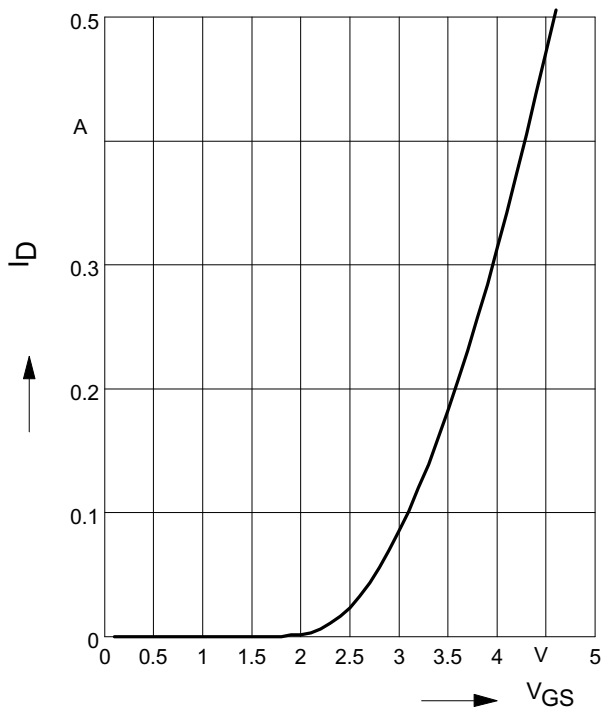
parameter: $T_j = 25\text{ }^\circ\text{C}$, V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

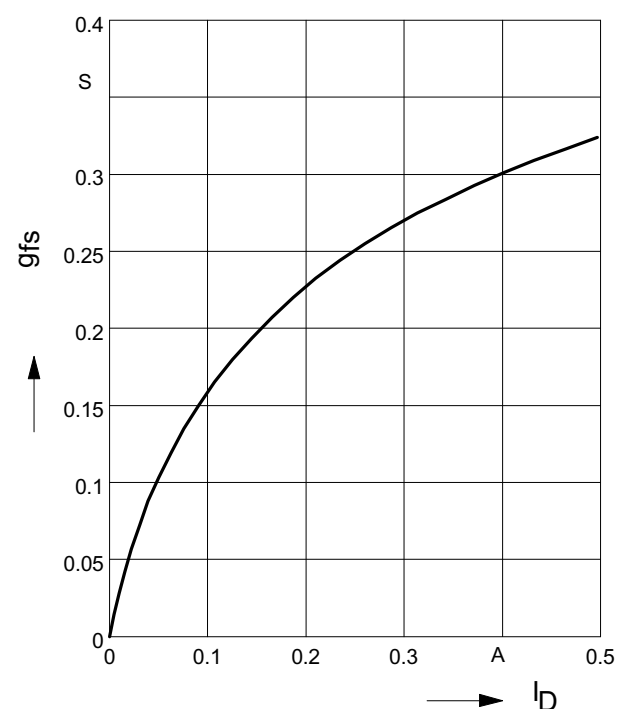
parameter: $T_j = 25\text{ }^\circ\text{C}$



8 Typ. forward transconductance

$g_{fs} = f(I_D)$

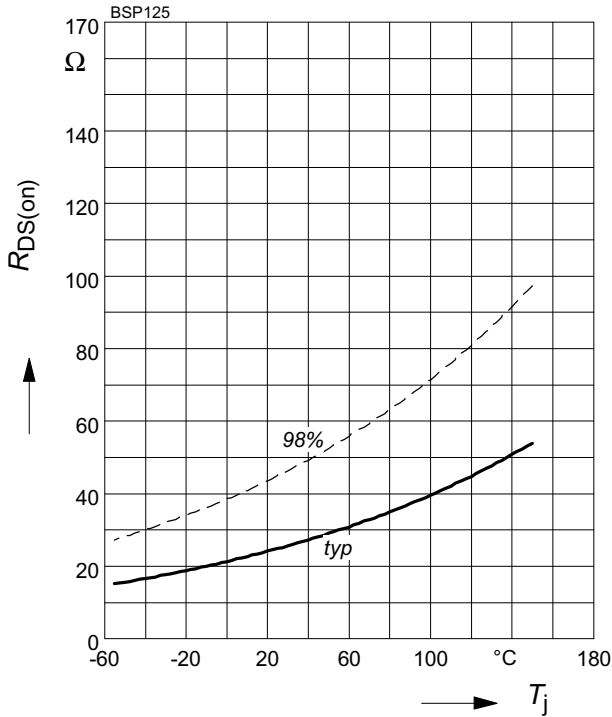
parameter: $T_j = 25\text{ }^\circ\text{C}$



9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

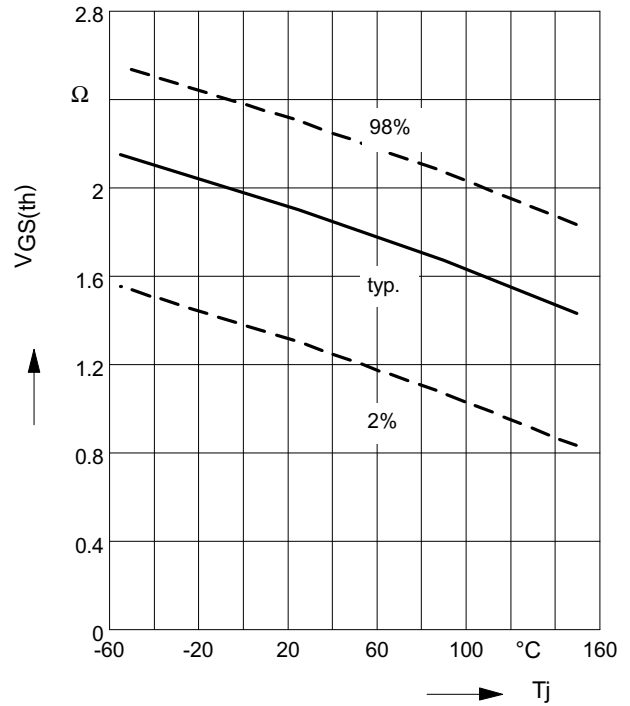
parameter : $I_D = 0.12 \text{ A}$, $V_{GS} = 10 \text{ V}$



(.) Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

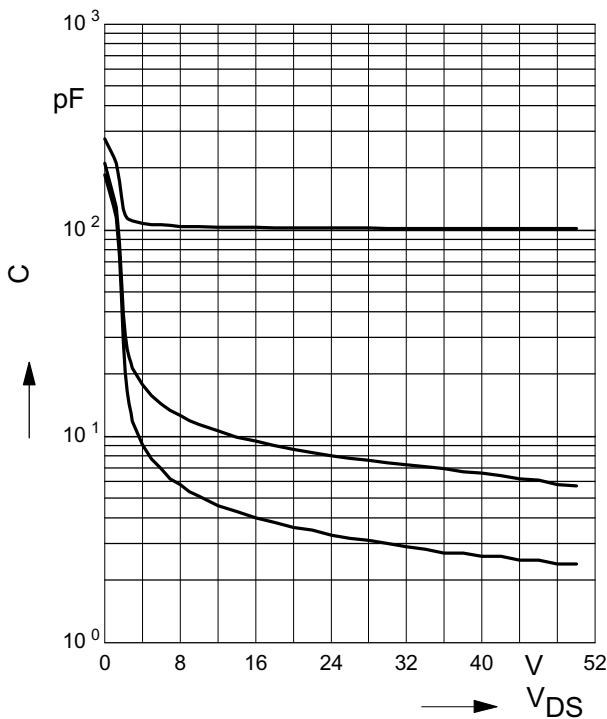
parameter: $V_{GS} = V_{DS}$; $I_D = 94 \mu\text{A}$



11 Typ. capacitances

$$C = f(V_{DS})$$

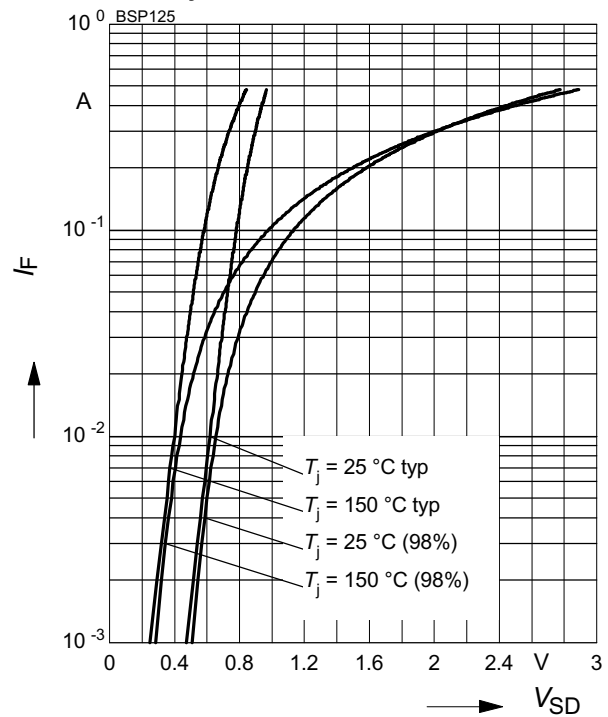
parameter: $V_{GS}=0$, $f=1 \text{ MHz}$, $T_j = 25 \text{ }^\circ\text{C}$



12 Forward character. of reverse diode

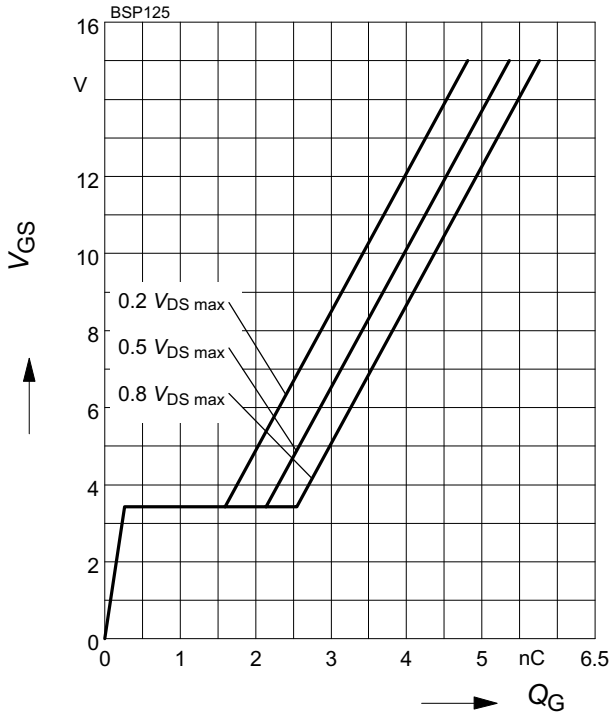
$$I_F = f(V_{SD})$$

parameter: T_j



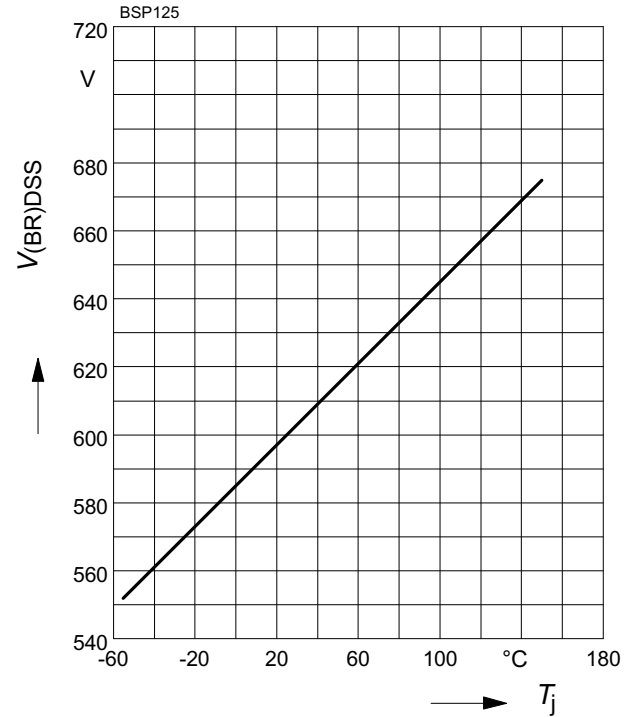
13 Typ. gate charge

$V_{GS} = f(Q_G)$; parameter: V_{DS} ,
 $I_D = 0.12 \text{ A pulsed}$, $T_j = 25 \text{ }^\circ\text{C}$



14 Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$



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